

REMARKS

Reconsideration and allowance of this application, as amended, is respectfully requested.

This amendment is in response to the Notice of Non-Responsive Reply, mailed June 26, 2008, as well as the October 26, 2007 Office Action. In this Notice of Non-Responsive Reply, the original reply filed on March 26, 2008 was objected to for failure to respond to all objections/rejections directed to claims 21 and 22. By the present Amendment, claim 21 has been amended in the same manner as claim 22, noting that claim 22 had been amended and argued in the March 26, 2008 Amendment. In addition, a minor correction has been made by the present Amendment to claim 14 since the original language of claim 14, as amended in the March 26, 2008 amendment had stated that "the through holes of the semiconductor substrate being located above the through holes of the semiconductor substrate." This has been corrected to define that "the through holes of the semiconductor substrate being located directly above the through holes of the multilayer wiring board." It is respectfully requested that the present re-submitted amendment be used to replace the amendment filed on March 26, 2008.

With regard to claims 21 and 22, it is noted that these claims correspond to features shown, for example, in figures such as Fig. 5, Fig. 7 and Fig. 8 (and described, for example, beginning on page 22 of the original specification, regarding the location of the thermal vias 4 of the multilayer wiring board relative to the actual heat dissipation areas from the transistor. Therefore, it is respectfully submitted that both the drawings and the specification provide a description of the claimed arrangement of the through

holes so that the in-plane distribution of heat dissipated from the transistor is substantially identical with an in-plane distribution of the through holes as defined in claims 21 and 22. Therefore, removal of the objections and rejections set forth in the October 26, 2007 Office Action regarding claims 21 and 22 is earnestly solicited.

Reconsideration and removal of the objection to the drawings, the objection to the Specification, and the 35 USC §112, first paragraph, rejections based on failure to comply with written description requirements and enablement requirements, is respectfully requested. By the present Amendment, each of the rejected independent claims has been amended to delete the language, which these various objections and rejections appear to be premised on, regarding entire areas which the through holes in the semiconductor substrate occupy being included in areas which only the through holes of the multilayer wiring board occupy. Instead, each of these claims has been amended to clearly define that it is areas of the through holes, projected onto the multilayer wiring board, which falls within the through holes of the multilayer wiring board. It is respectfully submitted that this is clearly illustrated in the drawing figures, including Figs. 2(C) and 5, as well as being supported by the discussion on page 19, line 5 et seq. It is also respectfully submitted that this claim language clearly defines over the cited prior art of record, and the admitted prior art of Fig. 4, none of which teach the claimed relationship regarding the projected areas. Therefore, reconsideration and allowance of each of the independent claims 14, 15, 16, 17, 21, 22, 23 and 26, together with their respective dependent claims, is respectfully requested.

In addition, it is noted that new dependent claims 50-54 are submitted which specifically define that the entirety of each of the projected areas in an XY plane

perpendicular to a Z axis of the multilayer wiring board, along which axis the through holes extend, are included in areas in the XY plane of the corresponding through holes in the multilayer wiring board. The current claim language is specifically drafted from the language used in page 19, line 5 et seq. of the Specification that:

“In the present invention, an entire area occupied by the via holes 5 is included in an area occupied by the thermal vias 4 in the XY plane in the Figure.”

As such, it is respectfully submitted that the language of these dependent claims is also clearly supported by the Specification and the drawings which this portion of the Specification refers to. Therefore, reconsideration and allowance of these newly presented dependent claims 50-54 is also respectfully requested.

With regard to the newly submitted dependent claims, it is noted that on page 16 of the Office Action, it is stated that the previous arguments with regard to page 19, line 5 et seq., were “deemed unpersuasive because the scope of the claims is not so limited.” Accordingly, the new dependent claims 50-54 have been specifically drafted to include the language used in the specification with regard to the areas in the XY plane of the figures, clearly shown in Fig. 2(c). Therefore, it is urged that these dependent claims very clearly correspond to the Specification and the drawings, and, as such, entry of these claims, removal of the objections and rejections previously set forth in the Office Action, and allowance of these claims, together with their respective parent claims, is earnestly solicited.


If the Examiner believes that there are any other points which may be clarified or otherwise disposed of either by telephone discussion or by personal interview, the

Examiner is invited to contact Applicants' undersigned attorney at the number indicated below.

To the extent necessary, Applicants petition for an extension of time under 37 CFR 1.136. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Antonelli, Terry, Stout & Kraus, LLP Deposit Account No. 01-2135 (Docket No. 500.40530X00), and please credit any excess fees to such deposit account.

Respectfully submitted,
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